AON7444
60V N-Channel MOSFET

General Description

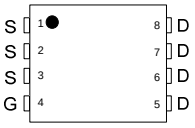
The AON7444 is fabricated with SDMOS™ trench technology that combines excellent $R_{DS(ON)}$ with low gate charge and low Qrr.The result is outstanding efficiency with controlled switching behavior. This universal technology is well suited for PWM, load switching and general purpose applications.

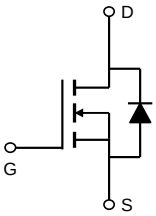
Features

V_{DS}	60V
I_D (at V_{GS}=10V)	33A
$R_{DS(ON)}$ (at V_{GS}=10V)	< 22mΩ
$R_{DS(ON)}$ (at V_{GS}=4.5V)	< 26mΩ

Green Product

Top View





Absolute Maximum Ratings T_A=25℃ unless otherwise noted				
Parameter		**Symbol**	**Maximum**	**Units**
Drain-Source Voltage		V_{DS}	60	V
Gate-Source Voltage		V_{GS}	±20	V
Continuous Drain Current	T_C=25℃	I_D	33	A
	T_C=100℃		21	
Pulsed Drain Current [C]		I_{DM}	75	
Continuous Drain Current	T_A=25℃	I_{DSM}	9	A
	T_A=70℃		7	
Avalanche Current [C]		I_{AS}, I_{AR}	30	A
Avalanche energy L=0.1mH [C]		E_{AS}, E_{AR}	45	mJ
Power Dissipation [B]	T_C=25℃	P_D	42	W
	T_C=100℃		17	
Power Dissipation [A]	T_A=25℃	P_{DSM}	3.1	W
	T_A=70℃		2	
Junction and Storage Temperature Range		T_J, T_{STG}	-55 to 150	℃

Thermal Characteristics					
Parameter		**Symbol**	**Typ**	**Max**	**Units**
Maximum Junction-to-Ambient [A]	t ≤ 10s	$R_{\theta JA}$	30	40	℃/W
Maximum Junction-to-Ambient [A D]	Steady-State		60	75	℃/W
Maximum Junction-to-Case	Steady-State	$R_{\theta JC}$	2.5	3	℃/W

Electrical Characteristics (T_J=25℃ unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
STATIC PARAMETERS						
BV_{DSS}	Drain-Source Breakdown Voltage	I_D=250µA, V_{GS}=0V	60			V
I_{DSS}	Zero Gate Voltage Drain Current	V_{DS}=60V, V_{GS}=0V			10	µA
		T_J=55℃			50	
I_{GSS}	Gate-Body leakage current	V_{DS}=0V, V_{GS}= ±20V			±100	nA
$V_{GS(th)}$	Gate Threshold Voltage	V_{DS}=V_{GS} I_D=250µA	1.5	2	2.6	V
$I_{D(ON)}$	On state drain current	V_{GS}=10V, V_{DS}=5V	75			A
$R_{DS(ON)}$	Static Drain-Source On-Resistance	V_{GS}=10V, I_D=9A		18	22	mΩ
		T_J=125℃		28	34	
		V_{GS}=4.5V, I_D=8A		20.5	26	mΩ
g_{FS}	Forward Transconductance	V_{DS}=5V, I_D=9A		45		S
V_{SD}	Diode Forward Voltage	I_S=1A,V_{GS}=0V		0.7	1	V
I_S	Maximum Body-Diode Continuous Current [G]				40	A
DYNAMIC PARAMETERS						
C_{iss}	Input Capacitance	V_{GS}=0V, V_{DS}=30V, f=1MHz	1340	1680	2000	pF
C_{oss}	Output Capacitance		100	150	195	pF
C_{rss}	Reverse Transfer Capacitance		35	60	85	pF
R_g	Gate resistance	V_{GS}=0V, V_{DS}=0V, f=1MHz	0.4	0.9	1.4	Ω
SWITCHING PARAMETERS						
Q_g(10V)	Total Gate Charge	V_{GS}=10V, V_{DS}=30V, I_D=9A	22	28	34	nC
Q_g(4.5V)	Total Gate Charge		10	13	16	nC
Q_{gs}	Gate Source Charge		5.5	6.9	8.3	nC
Q_{gd}	Gate Drain Charge		2	3.7	5	nC
$t_{D(on)}$	Turn-On DelayTime	V_{GS}=10V, V_{DS}=30V, R_L=3.3Ω, R_{GEN}=3Ω		6		ns
t_r	Turn-On Rise Time			2.4		ns
$t_{D(off)}$	Turn-Off DelayTime			24		ns
t_f	Turn-Off Fall Time			2.7		ns
t_{rr}	Body Diode Reverse Recovery Time	I_F=9A, dI/dt=500A/µs	9	13	17	ns
Q_{rr}	Body Diode Reverse Recovery Charge	I_F=9A, dI/dt=500A/µs	24	34	44	nC

A. The value of $R_{\theta JA}$ is measured with the device mounted on 1in^2 FR-4 board with 2oz. Copper, in a still air environment with T_A =25℃. The Power dissipation P_{DSM} is based on $R_{\theta JA}$ t ≤ 10s value and the maximum allowed junction temperature of 150℃. The value in any given application depends on the user's specific board design, and the maximum temperature of 150℃ may be u sed if the PCB allows it.

B. The power dissipation P_D is based on $T_{J(MAX)}$=150℃, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heatsinking is used.

C. Repetitive rating, pulse width limited by junction temperature $T_{J(MAX)}$=150℃. Ratings are based on low frequency and duty cycles to keep initial T_J =25℃.

D. The $R_{\theta JA}$ is the sum of the thermal impedence from junction to case $R_{\theta JC}$ and case to ambient.

E. The static characteristics in Figures 1 to 6 are obtained using <300µs pulses, duty cycle 0.5% max.

F. These curves are based on the junction-to-case thermal impedence which is measured with the device mounted to a large heatsink, assuming a maximum junction temperature of $T_{J(MAX)}$=150℃. The SOA curve provides a single pulse ratin g.

G. The maximum current rating is package limited.

H. These tests are performed with the device mounted on 1 in^2 FR-4 board with 2oz. Copper, in a still air environment with T_A=25℃.

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

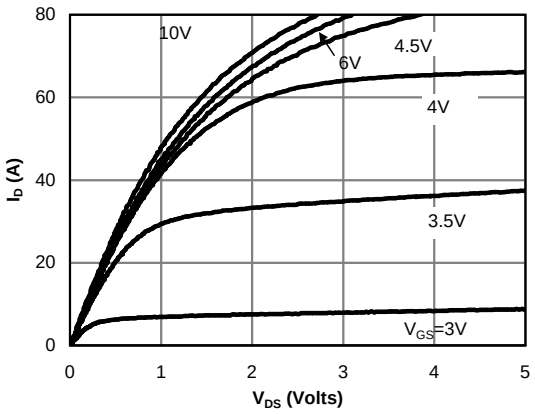


Fig 1: On-Region Characteristics (Note E)

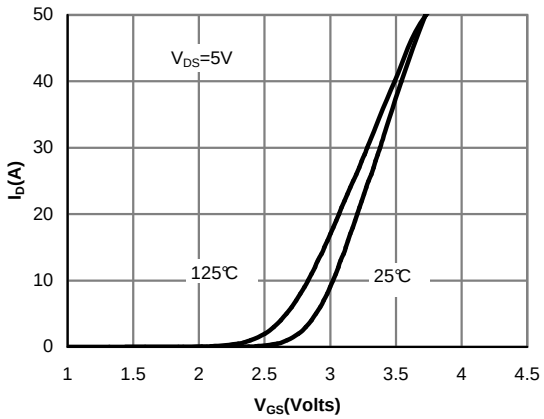


Figure 2: Transfer Characteristics (Note E)

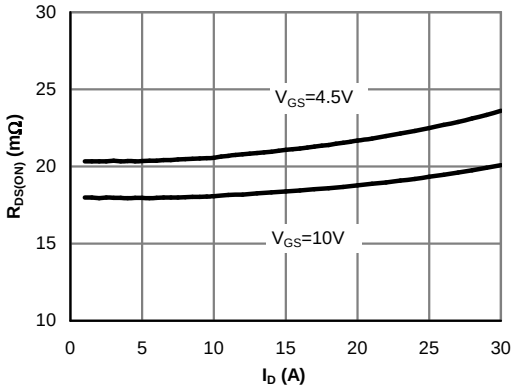


Figure 3: On-Resistance vs. Drain Current and Gate Voltage (Note E)

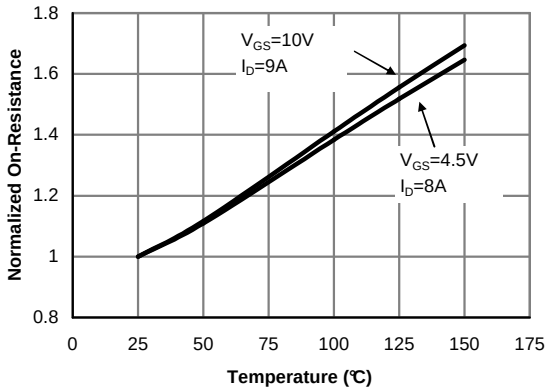


Figure 4: On-Resistance vs. Junction Temperature (Note E)

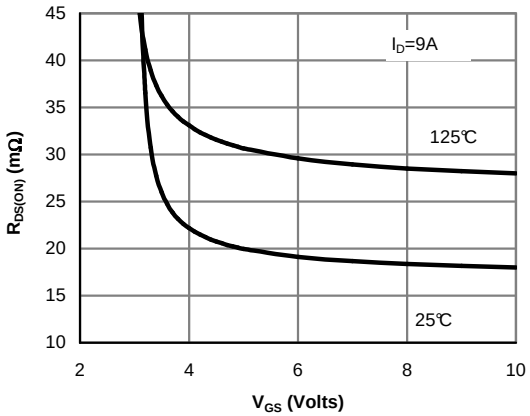


Figure 5: On-Resistance vs. Gate-Source Voltage (Note E)

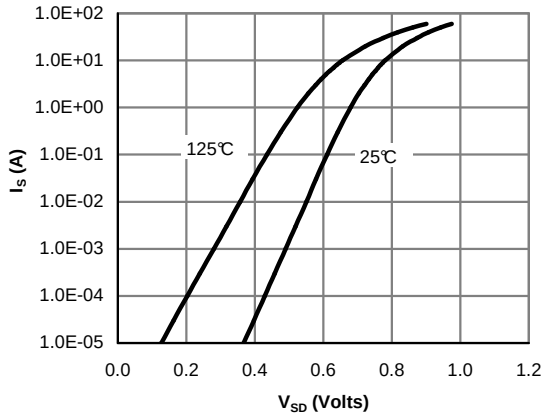


Figure 6: Body-Diode Characteristics (Note E)

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

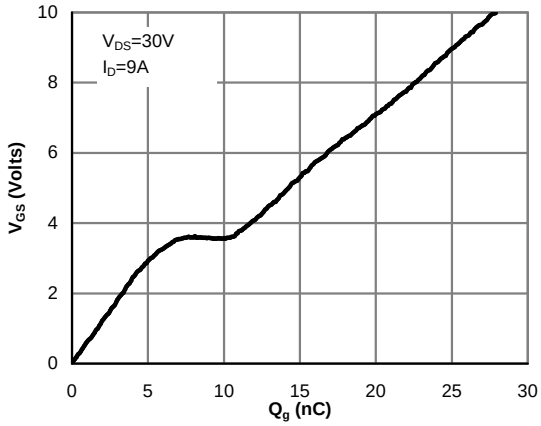


Figure 7: Gate-Charge Characteristics

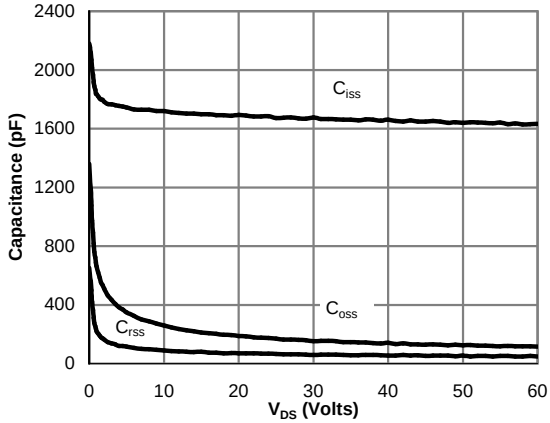


Figure 8: Capacitance Characteristics

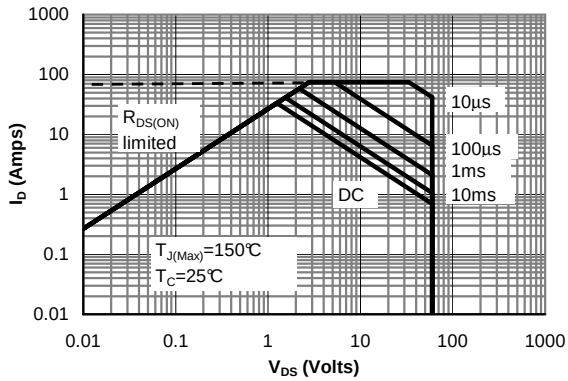


Figure 9: Maximum Forward Biased Safe Operating Area (Note F)

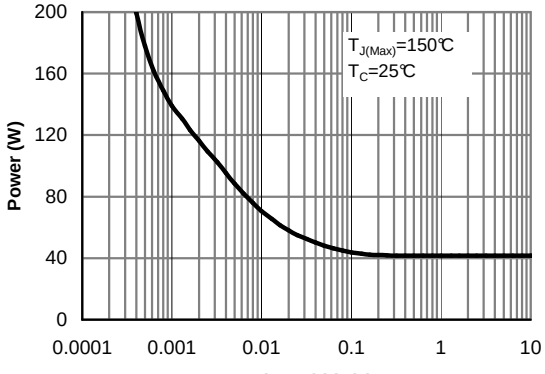


Figure 10: Single Pulse Power Rating Junction-to-Case (Note F)

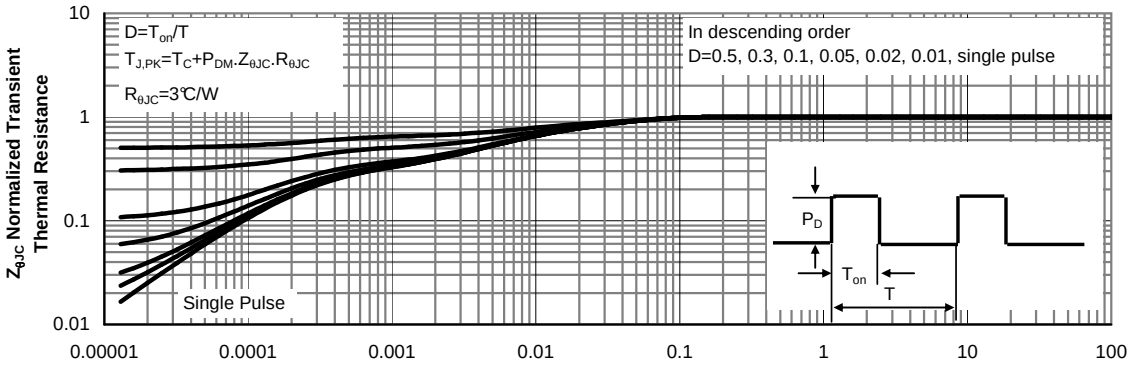


Figure 11: Normalized Maximum Transient Thermal Impedance (Note F)

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

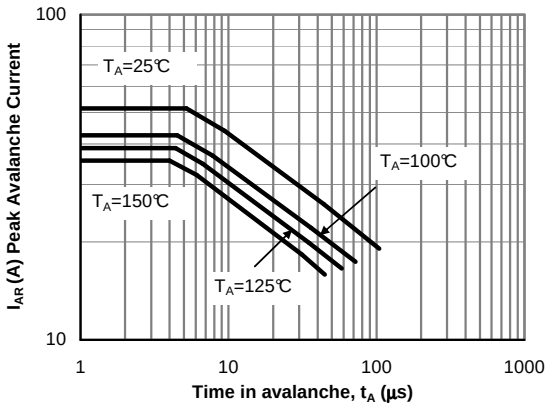


Figure 12: Single Pulse Avalanche capability (Note C)

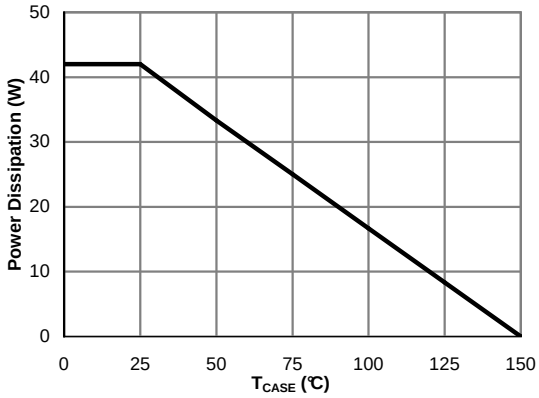


Figure 13: Power De-rating (Note F)

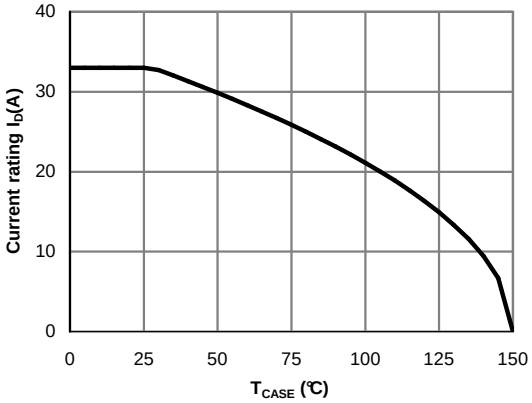


Figure 14: Current De-rating (Note F)

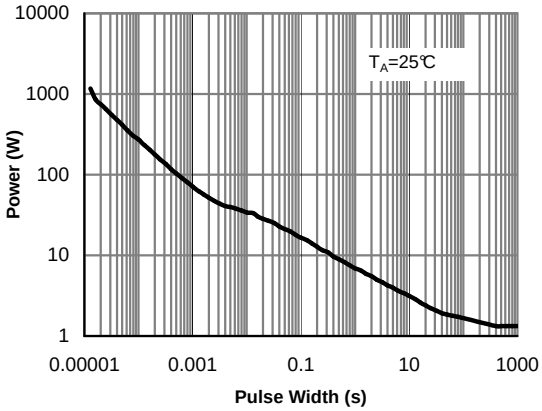


Figure 15: Single Pulse Power Rating Junction-to-Ambient (Note H)

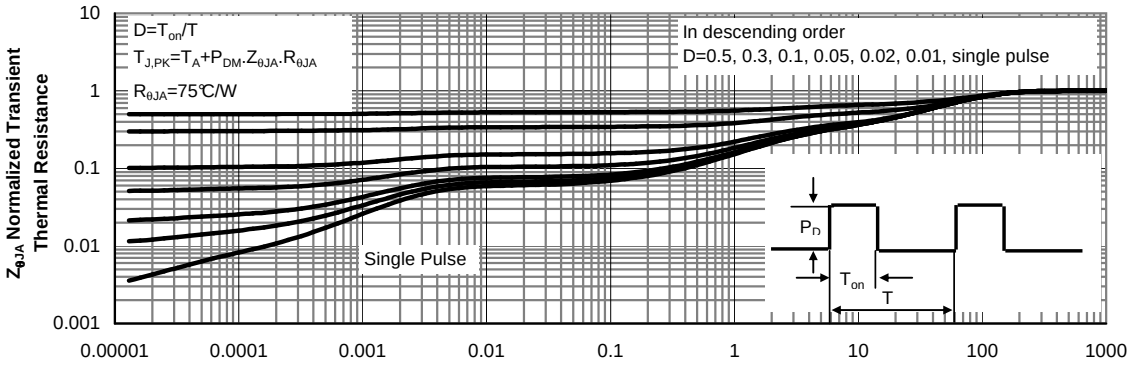


Figure 16: Normalized Maximum Transient Thermal Impedance (Note H)

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

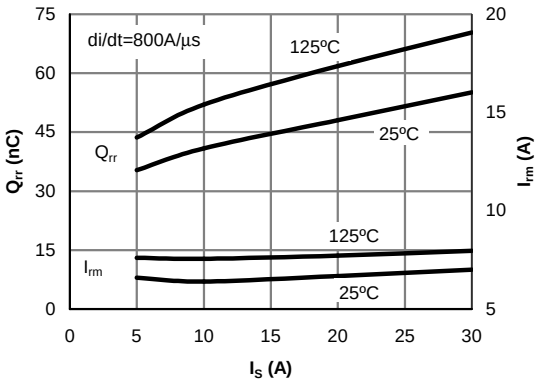


Figure 17: Diode Reverse Recovery Charge and Peak Current vs. Conduction Current

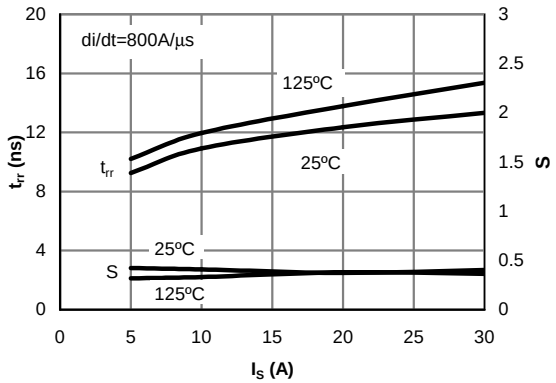


Figure 18: Diode Reverse Recovery Time and Softness Factor vs. Conduction Current

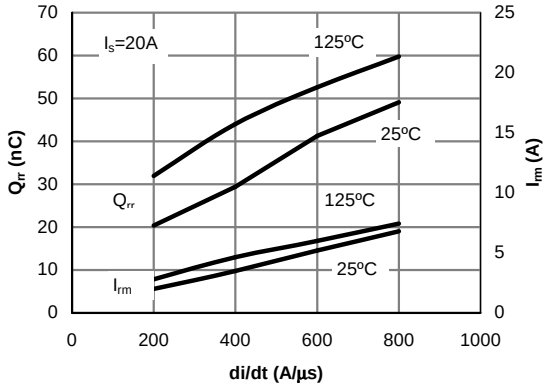


Figure 19: Diode Reverse Recovery Charge and Peak Current vs. di/dt

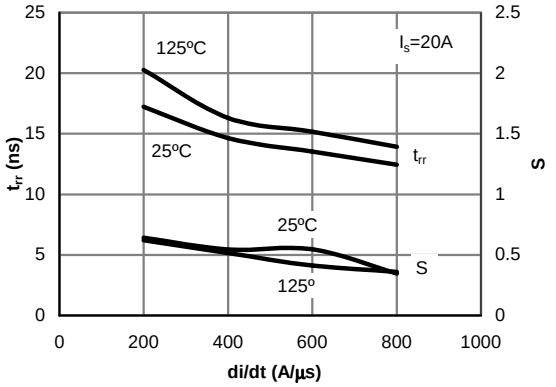
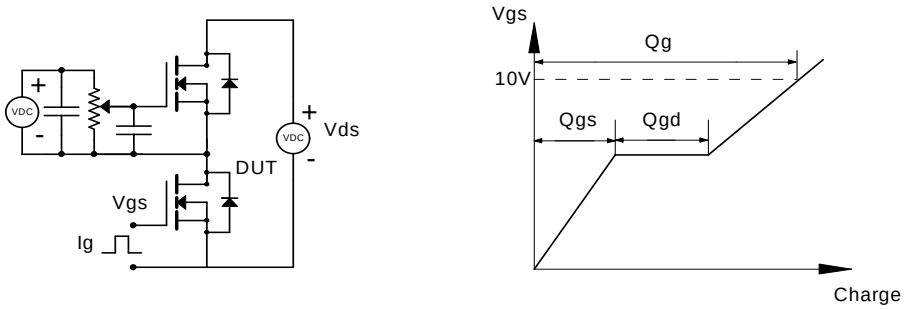
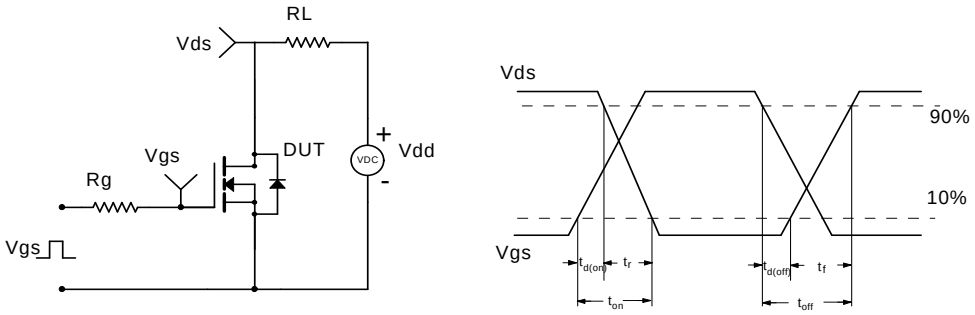


Figure 20: Diode Reverse Recovery Time and Softness Factor vs. di/dt

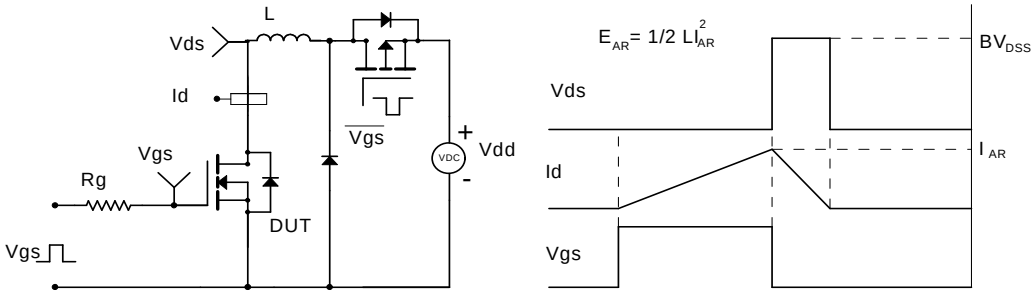
Gate Charge Test Circuit & Waveform



Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms